

ABSTRACT OF THE DISCLOSURE

A chip electronic component capable of being mounted with high density while preventing separation of bonded portions caused by solder fillets without requiring a case member having a complicated structure is provided at a low cost. The chip electronic component includes an electronic component element board including a circuit that defines an electronic component therein and having a pair of side surfaces and a lower surface, and a plurality of external electrodes extending over at least one of the side surface and the lower surface of the electronic component element and being electrically connected to the circuit provided therein. The electrode portion provided on the lower surface of the monolithic body as an electronic component element of each external electrode is provided with narrow portions and wide portions provided thereon, and the narrow portion continues to the external electrode portion provided on the side surface thereof.

RECORDED IN ELECTRONIC FORM